**Product Description**
Terratek® FX1504 is a unique elastomeric bioplastic with a diverse range of potential applications.

**Applications**
This material is suitable for injection molding, profile extrusion, sheet extrusion, blow molding, and 3D printer filament.

**Processing Recommendations**
Drying: Resin must be dried before processing.
Drying Conditions: Out of a sealed box: 90° to 100° F for 2 to 3 hours
Open box: 100° to 120° F for 4 to 5 hours

**Suggested Temperature Settings:**

<table>
<thead>
<tr>
<th>Extruder Zone</th>
<th>Rear</th>
<th>Center</th>
<th>Front</th>
<th>Nozzle</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature °F</td>
<td>300°-329°</td>
<td>300°-329°</td>
<td>300°-329°</td>
<td>300°-329°</td>
</tr>
</tbody>
</table>

Processing at temperatures above 350° F and in combination with high shear conditions such as high injection speed may result in thermal degradation of this resin.

Specific recommendation for processing FX1504 can be made based on customer equipment and processes. For further suggestions, please contact Green Dot.

**Property** | **Test Method** | **Value**
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Specific Gravity | ASTM D792 | 1.23 g/cm3
Izod Impact | ASTM D256 | 6.06 ft lb/in
Tensile Strength | ASTM D638 | 1,873 psi
Tensile Modulus | ASTM D638 | 16,097 psi
% Elongation | ASTM D790 | 400%
Flex Strength | ASTM D790 | 762 psi
Flex Modulus | ASTM D790 | 16,097 psi
Melt Index (190 C and 2160 g) | ASTM D1238 | 41.9 g/10 min
Shrinkage | .0095 in/in

**Packaging and Storing**
Terratek® FX1504 resin is typically packaged in a sealed plastic-lined fiber drum of 250 lbs. The product should be stored in a cool, dry, and sanitary area to achieve maximum stability.

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The information and recommendations in this sheet are based on our experience and analysis using standard procedures, and are believed to be accurate and reliable. However, they serve merely as typical guides, and are presented in good faith for the benefit of our customers. No guarantee, expressed or implied, is made regarding accuracy of the analysis, patent infringement, liabilities, or risks involved from the application of our products.

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